



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9616-TR	SNKU*UB62BA6	A	SH1A	2016-01-07
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	4.9x3.9x1.52	8	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	SNKU*UB62BA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.681	mg	supplier	die	Silicon (Si)	7440-21-3		3.573	mg	970660	44663
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	5433	250
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.011	mg	2988	138
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.048	mg	13040	600
Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.029	mg	7878	363
Leadframe	Copper & its alloys	16.777	mg	supplier	alloy	Copper (Cu)	7440-50-8		16.326	mg	973118	204075
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.384	mg	22888	4800
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.023	mg	1371	288
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.020	mg	1192	250
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.021	mg	1252	263
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	60	13
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	60	13
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	60	13
Die attach		1.156	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.052	mg	910035	13150
Die attach				supplier	glue or tape	acrylate	Proprietary		0.058	mg	50173	725
Die attach				supplier	glue or tape	Methacrylate	Proprietary		0.046	mg	39792	575
Bonding wire		0.145		supplier	wire	Gold (Au)	7440-57-5		0.145	mg	1000000	1813
encapsulation		58.213	mg	supplier	mold compound	Epoxy Resin	Proprietary		4.259	mg	73162	53238
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		4.259	mg	73162	53238
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		49.183	mg	844880	614788
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.284	mg	4879	3550
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.228	mg	3917	2850